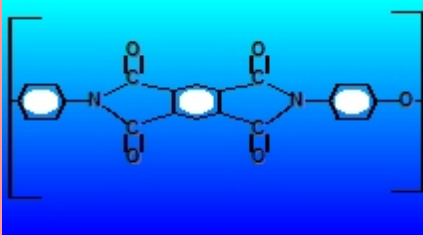


CALL FOR PAPERS

FIFTH INTERNATIONAL SYMPOSIUM ON POLYIMIDES AND OTHER HIGH TEMPERATURE POLYMERS

SYNTHESIS, CHARACTERIZATION AND APPLICATIONS
To be held November 5-7, 2007 in Orlando Florida, USA



This symposium is the fifth in a series the first of which was held in Newark, NJ in 1999. As with its predecessors, this symposium will be concerned with all aspects of polyimides and other high temperature polymers. These materials have found applications in such diverse areas as the aerospace industry and microelectronic components. A unique combination of physical and chemical properties make these materials highly attractive for demanding applications where chemical inertness, high temperature stability, low dielectric constant, mechanical toughness and processability are primary concerns. This symposium is organized to bring together scientists, technologists and engineers

TOPICS OF INTEREST INCLUDE:

- ▶ Chemistry, synthesis and characterization of polyimides and other high temperature polymers.
- ▶ Surface chemistry and surface modification

PHYSICO-CHEMICAL PROPERTIES

- ▶ Thermal-mechanical properties
- ▶ Electrical properties
- ▶ Adhesion properties and adhesion improvement
- ▶ Encapsulation and barrier properties
- ▶ Effects of aging and environment on long term stability, reliability and durability

APPLICATIONS

- ▶ Polyimides as adhesives and insulators.
- ▶ Polyimides as dielectrics, photoresists and encapsulants in microelectronic and biomedical structures
- ▶ Metallization of polyimide and investigation of interfaces.

NOVEL AND ADVANCED FORMULATIONS

- ▶ Ultralow dielectric materials, low thermal expansion liquid crystals, polyimide blends, nanocomposites, copolymers, foams,... etc.

interested in all aspects of high temperature polymers, to review and assess the current state of knowledge, to provide a forum for exchange and cross-fertilization of ideas, and to define problem areas which need intensified efforts. The invited speakers have been selected so as to represent widely differing disciplines and interests, and they hail from academic, governmental and industrial research laboratories. This meeting is planned to be a truly international event both in geographic coverage as well as in spirit. The technical program will contain both invited overviews and contributed original research papers. It is planned to chronicle the transactions in a hard-bound volume of archival quality (to match or exceed the standards of the journal literature) which will serve as a reference work for future generations of investigators.

This symposium is being organized by MST Conferences, LLC under the direction of Dr. K. L. Mittal, Editor, Journal of Adhesion Science and Technology. A proceedings volume is planned for this symposium and further details will be provided in due course. Please notify the conference chairman of your intentions to present a paper as early as possible. An abstract of about 200 words should be sent by **June 15, 2007** to the conference chairman by any of the following methods:

E-mail: rhl@mstconf.com
FAX: 212-656-1016
Regular mail:

Dr. Robert H. Lacombe
Conference Chairman
3 Hammer Drive
Hopewell Junction, NY 12533

Contact by phone: 845-897-1654
Full conference details and registration via the Internet will be maintained on our web site:

<http://mstconf.com/polyimd5.htm>

Or mail response form below to the conference chairman at the address above.

FIFTH INTERNATIONAL SYMPOSIUM ON POLYIMIDES

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 PRESENT A PAPER

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